



YEA SHIN TECHNOLOGY CO., LTD

YS0956ZBB

N-Channel Enhancement MOSFET

VDS= 100V, ID= 10A



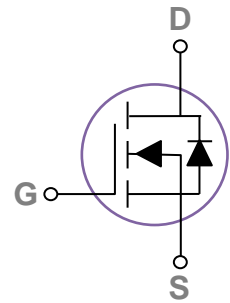
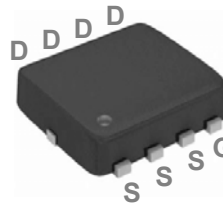
Features

- 100V, 10A, $R_{DS(ON)}=115m\Omega$ @ $V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications

PPAK3x3 Pin Configuration



Absolute Maximum Rating $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ\text{C}$) | 10 | A |
| | Drain Current – Continuous ($T_c=100^\circ\text{C}$) | 6.3 | A |
| I_{DM} | Drain Current – Pulsed ¹ | 40 | A |
| EAS | Single Pulse Avalanche Energy ² | 6 | mJ |
| IAS | Single Pulse Avalanche Current ² | 11 | A |
| P_D | Power Dissipation ($T_c=25^\circ\text{C}$) | 29.8 | W |
| | Power Dissipation – Derate above 25°C | 0.24 | W/ $^\circ\text{C}$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|---------------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 62 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 4.2 | $^\circ\text{C}/\text{W}$ |

DEVICE CHARACTERISTICS

YS0956ZBB

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|---|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 100 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =1mA | --- | 0.09 | --- | V/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =100V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =80V, V _{GS} =0V, T _J =125 °C | --- | --- | 10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |

On Characteristics

| | | | | | | |
|----------------------|--|--|-----|-----|-----|-------|
| R _{DS(ON)} | Static Drain-source On-Resistance ² | V _{GS} =10V, I _D =10A | --- | 90 | 115 | mΩ |
| | | V _{GS} =4.5V, I _D =8A | --- | 95 | 120 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.2 | 1.6 | 2.5 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -5 | --- | mV/°C |
| g _{fs} | Forward Transconductance | V _{DS} =10V, I _D =10A | --- | 8.7 | --- | S |

Dynamic and Switching Characteristics

| | | | | | | |
|---------------------|------------------------------------|---|-----|------|------|----|
| Q _g | Total Gate Charge ^{3,4} | V _{DS} =50V, V _{GS} =10V, I _D =2A | --- | 20 | 40 | nC |
| Q _{gs} | Gate-Source Charge ^{3,4} | | --- | 3.2 | 6 | |
| Q _{gd} | Gate-Drain Charge ^{3,4} | | --- | 3.6 | 7 | |
| T _{d(on)} | Turn-On Delay Time ^{3,4} | V _{DD} =50V, V _{GS} =10V, R _G =3.3 Ω, I _D =1A | --- | 18 | 36 | ns |
| T _r | Rise Time ^{3,4} | | --- | 4 | 8 | |
| T _{d(off)} | Turn-Off Delay Time ^{3,4} | | --- | 40 | 80 | |
| T _f | Fall Time ^{3,4} | | --- | 3 | 6 | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, f=1MHz | --- | 1400 | 2800 | pF |
| C _{oss} | Output Capacitance | | --- | 60 | 120 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 35 | 70 | |
| R _g | Gate Resistance | V _{GS} =0V, V _{DS} =0V, f=1MHz | --- | 2 | 4 | Ω |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--------------------------------------|--|------|------|------|------|
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | 10 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | 20 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1 | V |
| t _{rr} | Reverse Recovery Time ³ | V _{GS} =0V, I _S =1A, di/dt=100A/μs T _J =25°C | --- | 37 | --- | ns |
| Q _{rr} | Reverse Recovery Charge ³ | | --- | 27 | --- | nC |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=11A., R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

DEVICE CHARACTERISTICS

YS0956ZBB

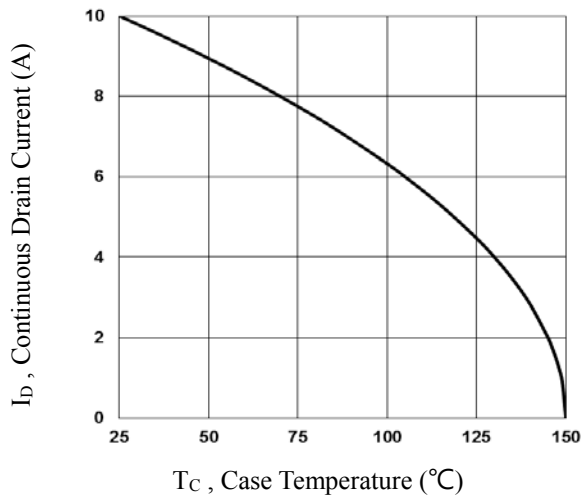


Fig.1 Continuous Drain Current vs. T_C

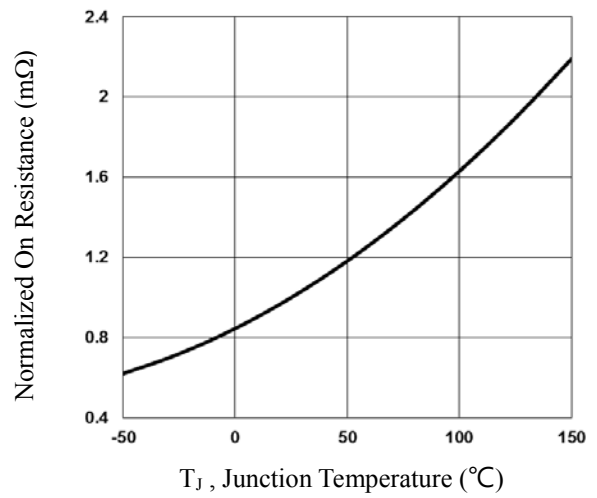


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

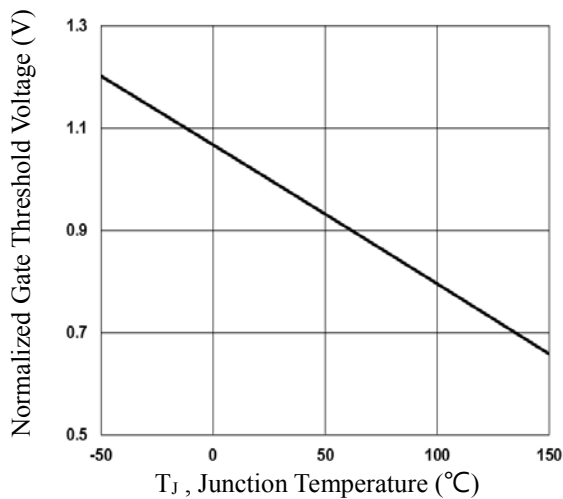


Fig.3 Normalized V_{th} vs. T_J

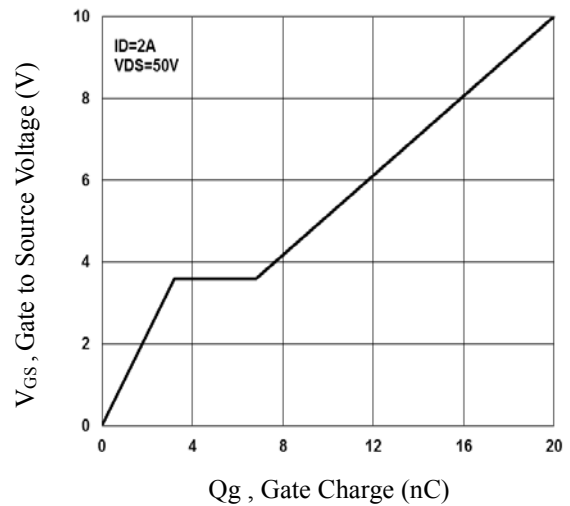


Fig.4 Gate Charge Waveform

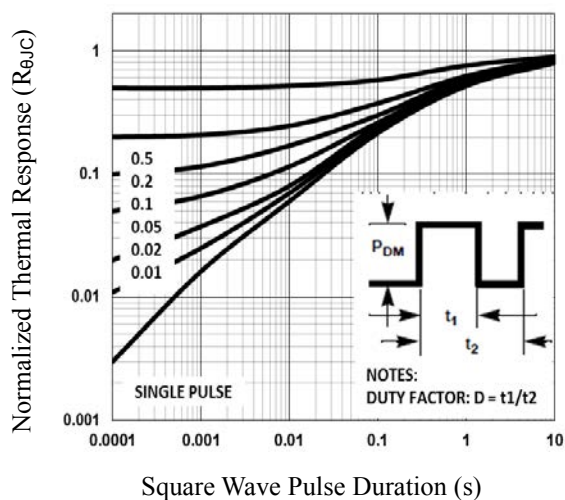


Fig.5 Normalized Transient Impedance

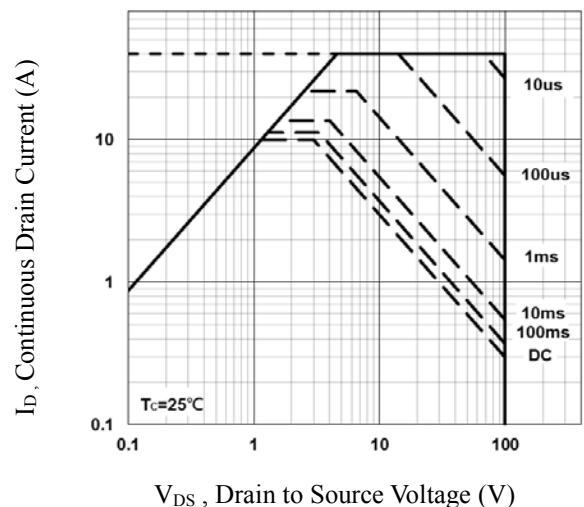


Fig.6 Maximum Safe Operation Area

DEVICE CHARACTERISTICS

YS0956ZBB

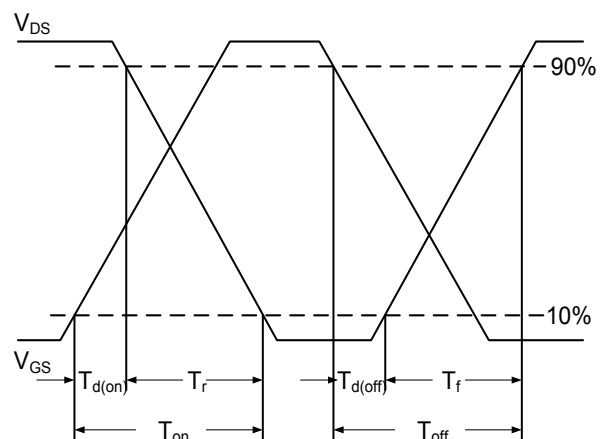


Fig.7 Switching Time Waveform

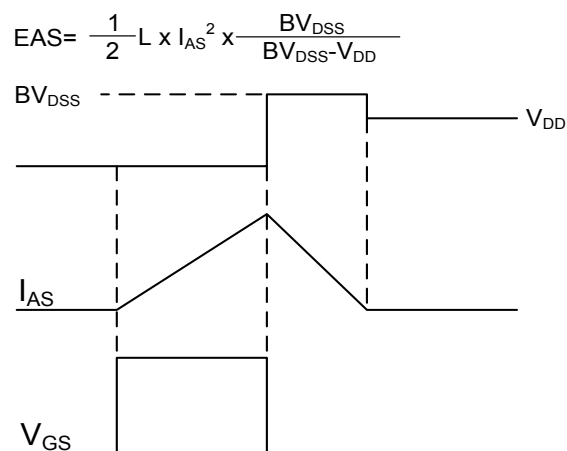


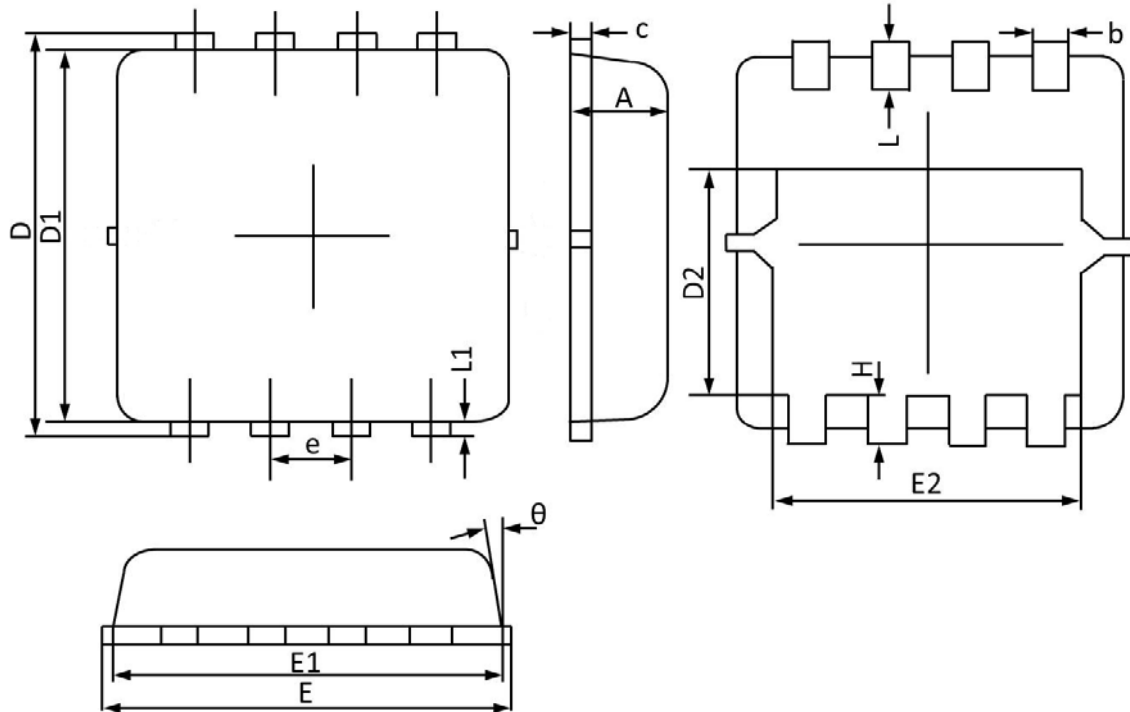
Fig.8 EAS Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

PACKAGE OUTLINE & DIMENSIONS

YS0956ZBB

PPAK3x3 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.700 | 0.900 | 0.028 | 0.035 |
| b | 0.240 | 0.350 | 0.009 | 0.014 |
| c | 0.100 | 0.250 | 0.004 | 0.010 |
| D | 3.050 | 3.450 | 0.120 | 0.136 |
| D1 | 2.900 | 3.200 | 0.114 | 0.126 |
| D2 | 1.350 | 1.850 | 0.053 | 0.073 |
| E | 3.000 | 3.400 | 0.118 | 0.134 |
| E1 | 2.900 | 3.250 | 0.114 | 0.128 |
| E2 | 2.350 | 2.600 | 0.093 | 0.102 |
| e | 0.650 BSC | | 0.026 BSC | |
| H | 0.300 | 0.500 | 0.012 | 0.020 |
| L | 0.300 | 0.500 | 0.012 | 0.020 |
| L1 | 0.070 | 0.200 | 0.003 | 0.008 |
| θ | 0° | 12° | 0° | 12° |